



TSFF5510

Vishay Semiconductors

## High Speed Infrared Emitting Diode, 870 nm, GaAlAs Double Hetero

### Description

TSFF5510 is an infrared, 870 nm emitting diode in GaAlAs double hetero (DH) technology with high radiant power and high speed, molded in a clear, untinted, plastic package.

### Features

- Package type: leaded
- Dimensions: T-1 $\frac{3}{4}$  ( $\varnothing$  5 mm)
- Peak wavelength:  $\lambda_p = 870$  nm
- High reliability
- High radiant power
- High radiant intensity
- Angle of half intensity:  $\varphi = \pm 38^\circ$
- Low forward voltage
- Suitable for high pulse current operation
- High modulation bandwidth
- Good spectral matching to Si photodetectors
- Lead (Pb)-free component in accordance with RoHS 2002/95/EC and WEEE 2002/96/EC



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### Applications

- Infrared video data transmission between camcorder and TV set
- Free air data transmission systems with high modulation frequencies or high data transmission

### Product Summary

Component	Symbol	Value	Unit
TSFF5510	$\phi_e$	55	mW
	$I_e$	32	mW/sr
	$t_r, t_f$	15	ns
	$\varphi$	$\pm 38$	deg
	$\lambda_p$	870	nm

### Ordering Information

Ordering code	Packing	Remarks
TSFF5510	Bulk	MOQ: 4000 pcs, 4000 pcs/bulk

Note:

MOQ: minimum order quantity

### Absolute Maximum Ratings

 $T_{amb} = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Test condition	Symbol	Value	Unit
Reverse voltage		$V_R$	5	V
Forward current		$I_F$	100	mA
Peak forward current	$t_p/T = 0.5, t_p = 100 \mu\text{s}$	$I_{FM}$	200	mA
Surge forward current	$t_p = 100 \mu\text{s}$	$I_{FSM}$	1	A
Power dissipation		$P_V$	170	mW
Junction temperature		$T_j$	100	$^\circ\text{C}$
Operating temperature range		$T_{amb}$	- 40 to + 85	$^\circ\text{C}$
Storage temperature range		$T_{stg}$	- 40 to + 100	$^\circ\text{C}$
Soldering temperature	$t \leq 5$ s, 2 mm from case	$T_{sd}$	260	$^\circ\text{C}$
Thermal resistance junction/ambient	J-STD-051, leads 7 mm soldered on PCB	$R_{thJA}$	250	K/W

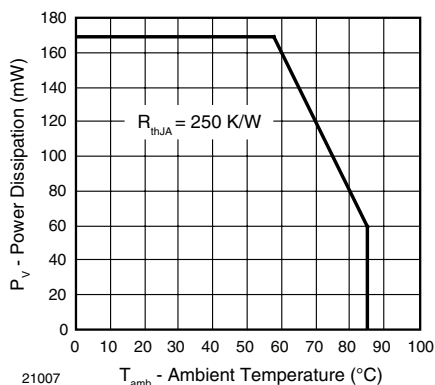


Figure 1. Power Dissipation Limit vs. Ambient Temperature

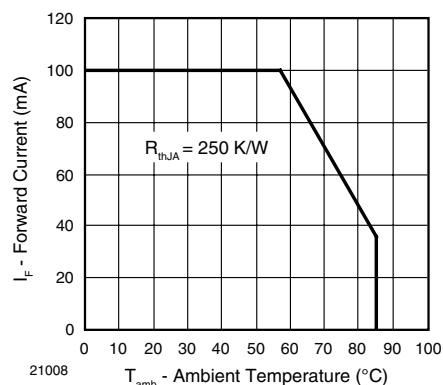


Figure 2. Forward Current Limit vs. Ambient Temperature

## Electrical Characteristics

T<sub>amb</sub> = 25 °C, unless otherwise specified

Parameter	Test condition	Symbol	Min.	Typ.	Max.	Unit
Forward voltage	I <sub>F</sub> = 100 mA, t <sub>p</sub> = 20 ms	V <sub>F</sub>	1.3	1.45	1.7	V
	I <sub>F</sub> = 450 mA, t <sub>p</sub> = 100 μs	V <sub>F</sub>	1.5	1.75	2.1	V
	I <sub>F</sub> = 1 A, t <sub>p</sub> = 100 μs	V <sub>F</sub>		2.1		V
Temperature coefficient of V <sub>F</sub>	I <sub>F</sub> = 1 mA	TK <sub>V<sub>F</sub></sub>		- 1.8		mV/K
Reverse current	V <sub>R</sub> = 5 V	I <sub>R</sub>			10	μA
Junction capacitance	V <sub>R</sub> = 0 V, f = 1 MHz, E = 0	C <sub>j</sub>		110		pF

## Optical Characteristics

T<sub>amb</sub> = 25 °C, unless otherwise specified

Parameter	Test condition	Symbol	Min.	Typ.	Max.	Unit
Radiant intensity	I <sub>F</sub> = 100 mA, t <sub>p</sub> = 20 ms	I <sub>e</sub>		32		mW/sr
Radiant power	I <sub>F</sub> = 100 mA, t <sub>p</sub> = 20 ms	φ <sub>e</sub>	44	55	89	mW
	I <sub>F</sub> = 450 mA, t <sub>p</sub> = 100 μs	φ <sub>e</sub>	200	247	400	mW
	I <sub>F</sub> = 1 A, t <sub>p</sub> = 100 μs	φ <sub>e</sub>		550		mW
Temperature coefficient of φ <sub>e</sub>	I <sub>F</sub> = 100 mA	TKφ <sub>e</sub>		- 0.35		%/K
Angle of half intensity		φ		± 38		deg
Peak wavelength	I <sub>F</sub> = 100 mA	λ <sub>p</sub>		870		nm
Spectral bandwidth	I <sub>F</sub> = 100 mA	Δλ		55		nm
Temperature coefficient of λ <sub>p</sub>	I <sub>F</sub> = 100 mA	TKλ <sub>p</sub>		0.25		nm/K
Rise time	I <sub>F</sub> = 100 mA	t <sub>r</sub>		15		ns
Fall time	I <sub>F</sub> = 100 mA	t <sub>f</sub>		15		ns
Cut-off frequency	I <sub>DC</sub> = 70 mA, I <sub>AC</sub> = 30 mA pp	f <sub>c</sub>		23		MHz



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## Basic Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified

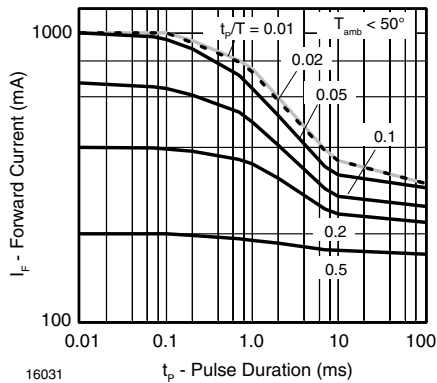


Figure 3. Pulse Forward Current vs. Pulse Duration

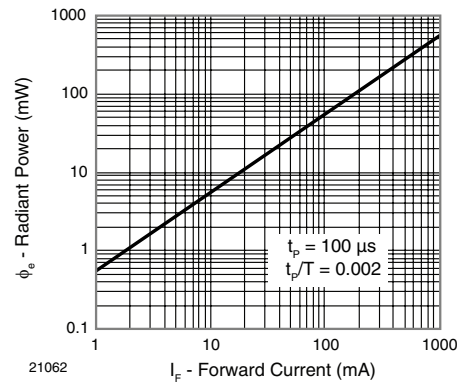


Figure 6. Radiant Power vs. Forward Current

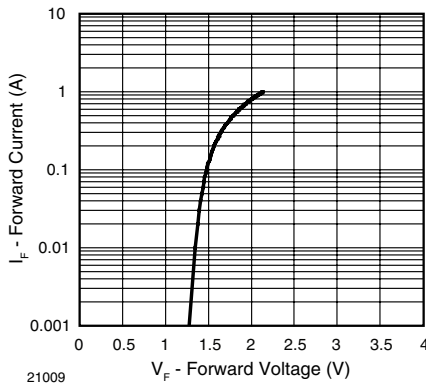


Figure 4. Forward Current vs. Forward Voltage

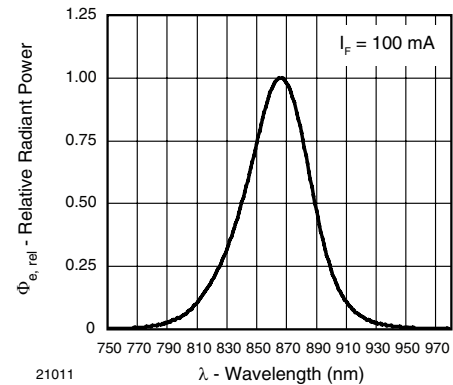


Figure 7. Relative Radiant Power vs. Wavelength

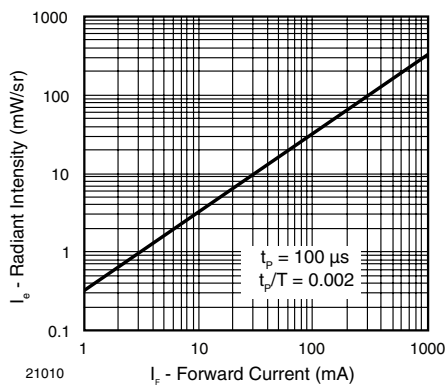


Figure 5. Radiant Intensity vs. Forward Current

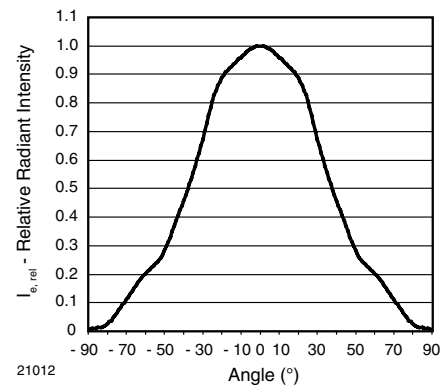


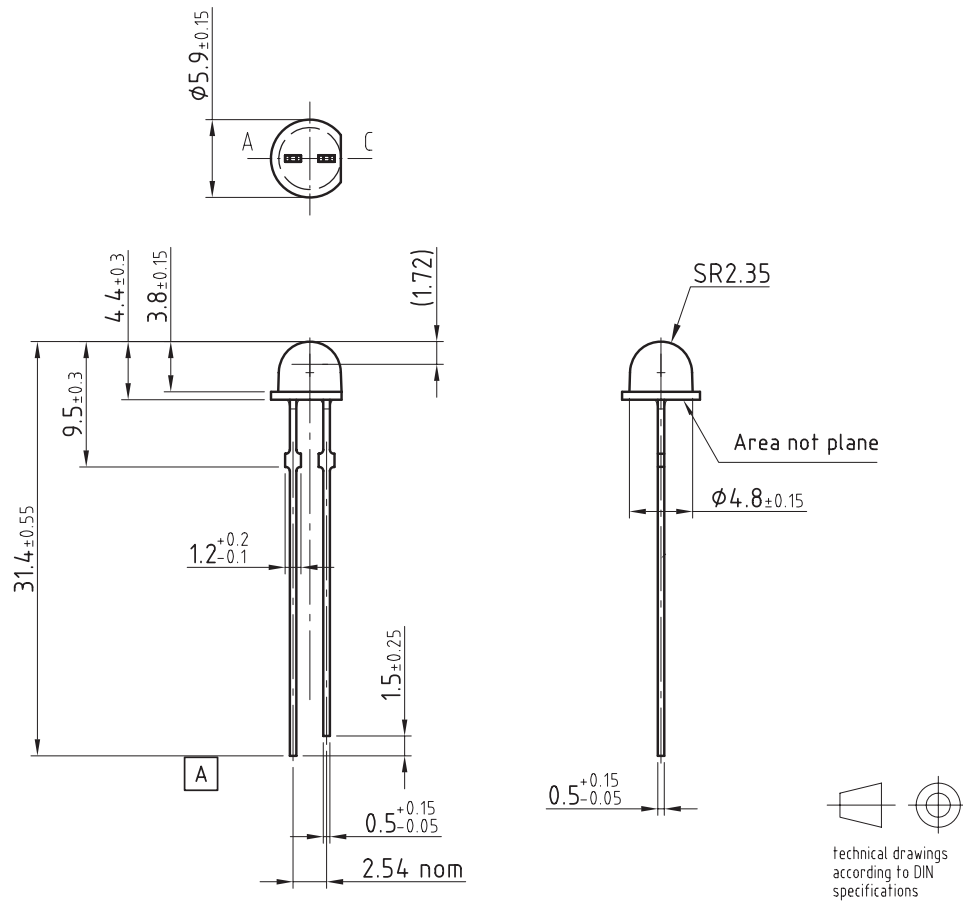
Figure 8. Relative Radiant Intensity vs. Angular Displacement

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## Package Dimensions in millimeters



Drawing-No.: 6.544-5390.01-4

19.07.07

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## Ozone Depleting Substances Policy Statement

It is the policy of Vishay Semiconductor GmbH to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively.
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA.
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design  
and may do so without further notice.

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Vishay Semiconductor GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany



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